NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
NOTES: (continued)

3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
4. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
5. Vias are optional depending on application, refer to device data sheet. If some or all are implemented, recommended via locations are shown.
NOTES: (continued)

6. For alternate stencil design recommendations, see IPC-7525 or board assembly site preference.
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